

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	3220	rewiring	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 17:09
L2	3737	rewiring re adj wiring	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 17:09
L3	852469	bump ball stud	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 17:10
L4	1662223	width	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 17:11
L5	37152	(rewir\$4 re adj wir\$4 redistribut\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 17:13
L6	6225587	(wiring wire metal metalization metallization conduct\$3 interconnect\$4 inter adj2 connect\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 17:14
L7	56978	4 near3 6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 17:15
L8	486	3 with 7	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 17:15
L9	1	8 same 1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 17:23

L10	3	8 and 1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 17:16
L11	486	8 same 6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 17:24
L12	6	8 same 5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 17:24
S6	1	10/761310	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/20 10:41
S7	2880	rewiring	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 17:09
S8	692374	bump ball	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 17:10
S9	4005921	width area	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/20 10:53
S10	8330670	(narrow\$2 wide\$2 big\$2 great\$2 large\$2 small\$2 thick\$2 thin\$2 different varying)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/20 10:55
S11	5574242	((multilevel\$4 multilayer\$4 (multi\$4 plural\$4) adj (layer\$4 level\$4)) adj (interconnect\$4 (inter adj connect\$4))) (wiring wire metal metalization metallization conduct\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/20 12:25

S12	82813	(bump ball) with (((multilevel\$4 multilayer\$4 (multi\$4 plural\$4) adj (layer\$4 level\$4)) adj (interconnect\$4 (inter adj connect\$4))) (wiring wire metal metalization metallization conduct\$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/20 12:27
S13	1032769	(width area) near3 ((narrow\$2 wide\$2 big\$2 great\$2 large\$2 small\$2 thick\$2 thin\$2 different varying))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/20 12:35
S14	3	"01120040"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/20 12:44
S15	4	10/761310 "01120040"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/20 12:43
S16	0	"1989120040"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/20 12:45
S17	0	"1989120040"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/20 12:45
S18	2	"2001120040"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/20 12:47
S19	985	((bump ball) with (((multilevel\$4 multilayer\$4 (multi\$4 plural\$4) adj (layer\$4 level\$4)) adj (interconnect\$4 (inter adj connect\$4))) (wiring wire metal metalization metallization conduct\$3))) with ((width area) near3 ((narrow\$2 wide\$2 big\$2 great\$2 large\$2 small\$2 thick\$2 thin\$2 different varying)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/20 12:47

S20	7	rewiring same (((bump ball) with (((multilevel\$4 multilayer\$4 (multi\$4 plural\$4) adj (layer\$4 level\$4)) adj (interconnect\$4 (inter adj connect\$4))) (wiring wire metal metalization metallization conduct\$3))) with ((width area) near3 ((narrow\$2 wide\$2 big\$2 great\$2 large\$2 small\$2 thick\$2 thin\$2 different varying))))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/20 12:50
S21	12	(((bump ball) with (((multilevel\$4 multilayer\$4 (multi\$4 plural\$4) adj (layer\$4 level\$4)) adj (interconnect\$4 (inter adj connect\$4))) (wiring wire metal metalization metallization conduct\$3))) with ((width area) near3 ((narrow\$2 wide\$2 big\$2 great\$2 large\$2 small\$2 thick\$2 thin\$2 different varying)))) and rewiring	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR •	ON	2004/09/20 13:51
S22	2211	((bump ball) with (((multilevel\$4 multilayer\$4 (multi\$4 plural\$4) adj (layer\$4 level\$4)) adj (interconnect\$4 (inter adj connect\$4))) (wiring wire metal metalization metallization conduct\$3))) same ((width area) near3 ((narrow\$2 wide\$2 big\$2 great\$2 large\$2 small\$2 thick\$2 thin\$2 different varying))))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/20 13:52
S23	139	((bump ball) with (((multilevel\$4 multilayer\$4 (multi\$4 plural\$4) adj (layer\$4 level\$4)) adj (interconnect\$4 (inter adj connect\$4))) (wiring wire metal metalization metallization conduct\$3))) and ((width area) near3 ((narrow\$2 wide\$2 big\$2 great\$2 large\$2 small\$2 thick\$2 thin\$2 different varying)))) and rewiring	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/20 13:52
S24	22	(((bump ball) with (((multilevel\$4 multilayer\$4 (multi\$4 plural\$4) adj (layer\$4 level\$4)) adj (interconnect\$4 (inter adj connect\$4))) (wiring wire metal metalization metallization conduct\$3))) same ((width area) near3 ((narrow\$2 wide\$2 big\$2 great\$2 large\$2 small\$2 thick\$2 thin\$2 different varying)))) and rewiring	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/20 13:55

S25	119	"3".clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/20 13:55
S26	21	(((bump ball) with (((multilevel\$4 multilayer\$4 (multi\$4 plural\$4) adj (layer\$4 level\$4)) adj (interconnect\$4 (inter adj connect\$4))) (wiring wire metal metalization metallization conduct\$3))) and ((width area) near3 ((narrow\$2 wide\$2 big\$2 great\$2 large\$2 small\$2 thick\$2 thin\$2 different varying))) and rewiring) and "3".clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/20 14:11
S27	15	(((bump ball) with (((multilevel\$4 multilayer\$4 (multi\$4 plural\$4) adj (layer\$4 level\$4)) adj (interconnect\$4 (inter adj connect\$4))) (wiring wire metal metalization metallization conduct\$3))) same rewiring) and "3".clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/20 14:11
S28	101	((bump ball) with (((multilevel\$4 multilayer\$4 (multi\$4 plural\$4) adj (layer\$4 level\$4)) adj (interconnect\$4 (inter adj connect\$4))) (wiring wire metal metalization metallization conduct\$3))) same rewiring	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/20 17:00
S29	1	10/052143 09/712105	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/20 17:08
S30	2	"6159837".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/20 17:24
S31	254	((bump ball) with (((multilevel\$4 multilayer\$4 (multi\$4 plural\$4) adj (layer\$4 level\$4)) adj (interconnect\$4 (inter adj connect\$4))) (wiring wire metal metalization metallization conduct\$3))) and rewiring	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/20 17:25

S32	34	"3".clm. and (((bump ball) with (((multilevel\$4 multilayer\$4 (multi\$4 plural\$4) adj (layer\$4 level\$4)) adj (interconnect\$4 (inter adj connect\$4))) (wiring wire metal metalization metallization conduct\$3))) and rewiring)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/20 17:26
S33	4186	rewir\$4 re adj wir\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/20 18:00
S34	158	"29".clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/20 17:33
S35	347	((bump ball) with (((multilevel\$4 multilayer\$4 (multi\$4 plural\$4) adj (layer\$4 level\$4)) adj (interconnect\$4 (inter adj connect\$4))) (wiring wire metal metalization metallization conduct\$3))) and (rewir\$4 re adj wir\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/20 17:33
S36	47	(((bump ball) with (((multilevel\$4 multilayer\$4 (multi\$4 plural\$4) adj (layer\$4 level\$4)) adj (interconnect\$4 (inter adj connect\$4))) (wiring wire metal metalization metallization conduct\$3))) and (rewir\$4 re adj wir\$4)) and "29".clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/20 17:55
S37	680837	land pad	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/20 17:56
S38	1635	(rewir\$4 re adj wir\$4) with (((multilevel\$4 multilayer\$4 (multi\$4 plural\$4) adj (layer\$4 level\$4)) adj (interconnect\$4 (inter adj connect\$4))) (wiring wire metal metalization metallization conduct\$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/20 17:57
S39	4065607	(insulat\$5 dielectric oxide) protect\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/20 17:57

S40	199	((rewir\$4 re adj wir\$4) with (((multilevel\$4 multilayer\$4 (multi\$4 plural\$4) adj (layer\$4 level\$4)) adj (interconnect\$4 (inter adj connect\$4))) (wiring wire metal metalization metallization conduct\$3))) with ((insulat\$5 dielectric oxide) protect\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/20 17:58
S41	46	"29".clm. and (((rewir\$4 re adj wir\$4) with (((multilevel\$4 multilayer\$4 (multi\$4 plural\$4) adj (layer\$4 level\$4)) adj (interconnect\$4 (inter adj connect\$4))) (wiring wire metal metalization metallization conduct\$3))) with ((insulat\$5 dielectric oxide) protect\$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/20 18:00
S42	153	((rewir\$4 re adj wir\$4) with (((multilevel\$4 multilayer\$4 (multi\$4 plural\$4) adj (layer\$4 level\$4)) adj (interconnect\$4 (inter adj connect\$4))) (wiring wire metal metalization metallization conduct\$3))) with ((insulat\$5 dielectric oxide) protect\$4)) not ("29".clm. and (((rewir\$4 re adj wir\$4) with (((multilevel\$4 multilayer\$4 (multi\$4 plural\$4) adj (layer\$4 level\$4)) adj (interconnect\$4 (inter adj connect\$4))) (wiring wire metal metalization metallization conduct\$3))) with ((insulat\$5 dielectric oxide) protect\$4)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/20 18:00
S43	1128	"29".ab.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/20 18:00

S44	86	(((((rewir\$4 re adj wir\$4) with (((multilevel\$4 multilayer\$4 (multi\$4 plural\$4) adj (layer\$4 level\$4)) adj (interconnect\$4 (inter adj connect\$4)))) (wiring wire metal metalization metallization conduct\$3))) with ((insulat\$5 dielectric oxide) protect\$4)) not ("29".clm. and (((rewir\$4 re adj wir\$4) with (((multilevel\$4 multilayer\$4 (multi\$4 plural\$4) adj (layer\$4 level\$4)) adj (interconnect\$4 (inter adj connect\$4)))) (wiring wire metal metalization metallization conduct\$3))) with ((insulat\$5 dielectric oxide) protect\$4)))) and "29".ab.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/21 07:39
S45	4	(((((rewir\$4 re adj wir\$4) with (((multilevel\$4 multilayer\$4 (multi\$4 plural\$4) adj (layer\$4 level\$4)) adj (interconnect\$4 (inter adj connect\$4)))) (wiring wire metal metalization metallization conduct\$3))) with ((insulat\$5 dielectric oxide) protect\$4)) not ("29".clm. and (((rewir\$4 re adj wir\$4) with (((multilevel\$4 multilayer\$4 (multi\$4 plural\$4) adj (layer\$4 level\$4)) adj (interconnect\$4 (inter adj connect\$4)))) (wiring wire metal metalization metallization conduct\$3))) with ((insulat\$5 dielectric oxide) protect\$4)))) and "29".ab.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/21 07:26
S46	5	"6545354".pn. "2003298005"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/21 08:00
S47	321	"WAKABAYASHI, TAKESHI".in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/21 08:00
S48	39905	casio.as.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/21 12:58

S49	3534	rewiring re-wiring	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/21 08:01
S50	3540	rewiring re adj wiring	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/06 17:09
S51	6	S50 not S49	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/21 08:03
S52	57	S47 and S48	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/21 08:03
S53	6	S52 and S50	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/21 12:28
S54	4310509	area thickness	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/21 08:06
S55	715200	bump ball	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/21 08:06
S56	3219687	larger greater	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/21 08:06
S57	8569649	(narrow\$2 wide\$2 big\$2 great\$2 large\$2 small\$2 thick\$2 thin\$2 different varying)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/21 08:09
S58	6094765	(wiring wire metal metalization metallization conduct\$3 interconnect\$4 inter adj2 connect\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/21 08:15

S59	4	((S57 near3 S54) with S50 with S58) same S55	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/21 09:10
S60	1061983	(S57 near3 S54)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/21 09:00
S61	1483	S50 with S58	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/21 09:21
S62	16	S60 with S61	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/21 09:21
S63	36	S60 same S61	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/21 09:21
S64	12	S63 same S55	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/21 09:22
S65	15	("20020096757" "5117280" "5172212" "5569960" "5977641" "6103552" "6184062" "6285083" "6326701" "6329288" "6351035" "6387734" "6395164" "6400019" "6479900").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/01/21 09:44
S66	35612	(rewir\$4 re adj wir\$4 redistribut\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/21 09:55
S67	4582	S66 with S58	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/21 09:57

S68	83	S67 with S60	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/21 09:57
S69	19	S68 same S55	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/21 10:21
S70	58	S68 and S55	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/21 10:22
S71	39	S70 not S69	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/21 10:27
S72	39	S71 and S66	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/21 10:46
S73	5	"20020111009" "01120040"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/21 10:54
S74	167107	uppermost upper adj most	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/21 10:55
S75	2986	S74 adj2 S58	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/21 10:57
S76	15	S75 same S66	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/21 10:57
S77	15	S76 and S66	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/21 12:28
S78	0	("6812565").URPN.	USPAT	OR	ON	2005/01/21 12:34

S79	1	("6388318").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/01/21 12:34
S80	0	("6545354").URPN.	USPAT	OR	ON	2005/01/21 12:34
S81	24	("4322778" "4617193" "4811082" "4903116" "5317433" "5530288" "5539241" "5770476" "5818079" "5928968" "5982018" "5990507" "6002161" "6025218" "6031293" "6108212" "6124606" "6140155" "6163456" "6180976" "6274937" "6331722" "6337517" "6362523").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/01/21 12:58
S82	2922780	width thickness	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/21 12:58
S83	4176407	"within"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/21 13:36
S84	120214	S58 near2 S82	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/21 14:31
S85	2907	S83 near8 S84	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/21 14:31
S86	15	S55 with S85	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/21 14:33
S87	2	S86 and S66	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/21 14:31